

HD74ALVC2G74

Single D-type Flip Flops with Preset and Clear

REJ03D0169-0300Z
(Previous ADE-205-639B (Z))
Rev.3.00
Dec.18.2003

Description

The HD74ALVC2G74 has independent data, preset, clear, and clock inputs Q and \overline{Q} outputs in an 8 pin package. The input data is transferred to the output at the rising edge of clock pulse CLK. Low voltage and high-speed operation is suitable for the battery powered products (e.g., notebook computers), and the low power consumption extends the battery life.

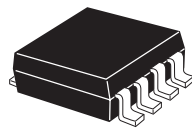
Features

- The basic gate function is lined up as Renesas uni logic series.
- Supplied on emboss taping for high-speed automatic mounting.
- Supply voltage range : 1.2 to 3.6 V
Operating temperature range: -40 to +85°C
- All inputs V_{IH} (Max.) = 3.6 V (@ V_{CC} = 0 V to 3.6 V)
All outputs V_O (Max.) = 3.6 V (@ V_{CC} = 0 V)
- Output current ± 2 mA (@ V_{CC} = 1.2 V)
 ± 4 mA (@ V_{CC} = 1.4 V to 1.6 V)
 ± 6 mA (@ V_{CC} = 1.65 V to 1.95 V)
 ± 18 mA (@ V_{CC} = 2.3 V to 2.7 V)
 ± 24 mA (@ V_{CC} = 3.0 V to 3.6 V)
- Ordering Information

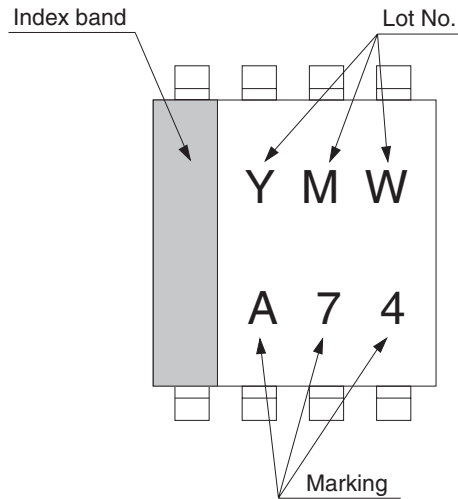
Part Name	Package Type	Package Code	Package Abbreviation	Taping Abbreviation (Quantity)
HD74ALVC2G74USE	SSOP-8 pin	TTP-8DBV	US	E (3,000 pcs/reel)

Outline and Article Indication

• HD74ALVC2G74



SSOP-8



Function Table

Inputs				Outputs	
$\overline{\text{PRE}}$	$\overline{\text{CLR}}$	CLK	D	Q	$\overline{\text{Q}}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H ^{*1}	H ^{*1}
H	H	↑	H	H	L
H	H	↑	L	L	H
H	H	↓	X	Q ₀	$\overline{\text{Q}}$ ₀

H : High level

L : Low level

X : Immaterial

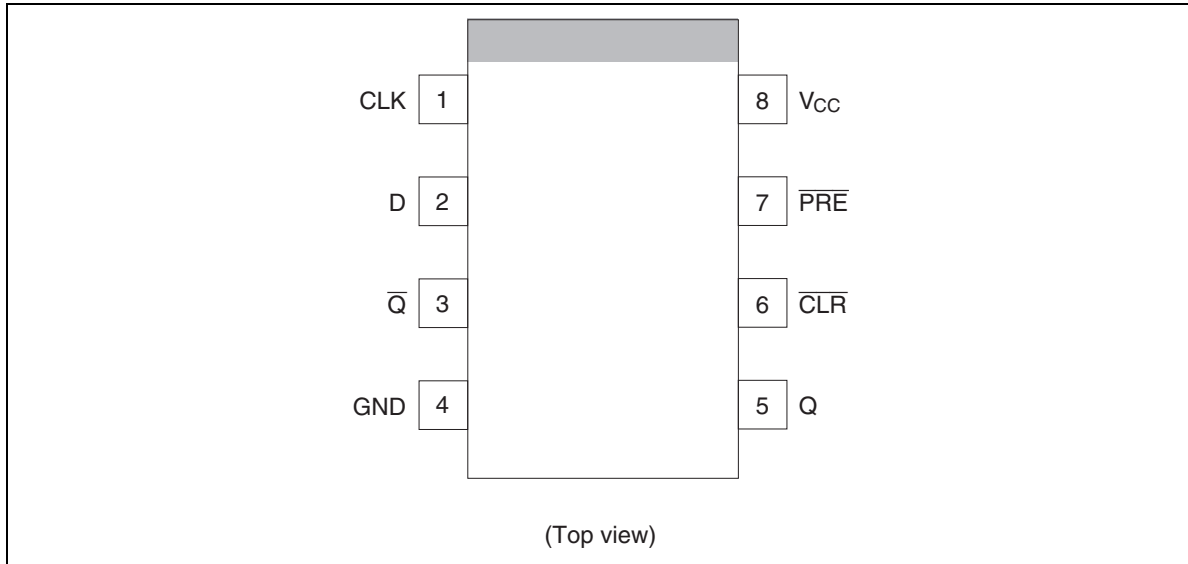
↑ : Low to high transition

↓ : High to low transition

Q₀ : The level of Q immediately before the input conditions shown in the above table are determined.

Note : 1. Q and $\overline{\text{Q}}$ will remain high as long as preset and clear are low, but Q and $\overline{\text{Q}}$ are unpredictable, if preset and clear go high simultaneously.

Pin Arrangement



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit	Conditions
Supply voltage range	V_{CC}	-0.5 to 4.6	V	
Input voltage range ^{*1}	V_I	-0.5 to 4.6	V	
Output voltage range ^{*1, 2}	V_O	-0.5 to $V_{CC}+0.5$ -0.5 to 4.6	V	Output : H or L V_{CC} : OFF
Input clamp current	I_{IK}	-50	mA	$V_I < 0$
Output clamp current	I_{OK}	± 50	mA	$V_O < 0$ or $V_O > V_{CC}$
Continuous output current	I_O	± 50	mA	$V_O = 0$ to V_{CC}
Continuous current through V_{CC} or GND	I_{CC} or I_{GND}	± 100	mA	
Maximum power dissipation at $T_a = 25^\circ\text{C}$ (in still air) ^{*3}	P_T	200	mW	
Storage temperature	T_{stg}	-65 to 150	$^\circ\text{C}$	

Notes: The absolute maximum ratings are values, which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

1. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This value is limited to 4.6 V maximum.
3. The maximum package power dissipation was calculated using a junction temperature of 150 $^\circ\text{C}$.

Electrical Characteristics

(Ta = -40 to 85°C)

Item	Symbol	V _{CC} (V) *	Min	Typ	Max	Unit	Test conditions
Input voltage	V _{IH}	1.2	V _{CC} ×0.75	—	—	V	
		1.4 to 1.6	V _{CC} ×0.7	—	—		
		1.65 to 1.95	V _{CC} ×0.7	—	—		
		2.3 to 2.7	1.7	—	—		
		3.0 to 3.6	2.0	—	—		
	V _{IL}	1.2	—	—	V _{CC} ×0.25		
		1.4 to 1.6	—	—	V _{CC} ×0.3		
		1.65 to 1.95	—	—	V _{CC} ×0.3		
		2.3 to 2.7	—	—	0.7		
		3.0 to 3.6	—	—	0.8		
Output voltage	V _{OH}	Min to Max	V _{CC} -0.2	—	—	V	I _{OH} = -100 μA
		1.2	0.9	—	—		I _{OH} = -2 mA
		1.4	1.1	—	—		I _{OH} = -4 mA
		1.65	1.2	—	—		I _{OH} = -6 mA
		2.3	1.7	—	—		I _{OH} = -18 mA
		3.0	2.2	—	—		I _{OH} = -24 mA
	V _{OL}	Min to Max	—	—	0.2		I _{OL} = 100 μA
		1.2	—	—	0.3		I _{OL} = 2 mA
		1.4	—	—	0.3		I _{OL} = 4 mA
		1.65	—	—	0.3		I _{OL} = 6 mA
		2.3	—	—	0.55		I _{OL} = 18 mA
		3.0	—	—	0.55		I _{OL} = 24 mA
Input current	I _{IN}	3.6	—	—	±5	μA	V _{IN} = 3.6 V or GND
Quiescent supply current	I _{CC}	3.6	—	—	10	μA	V _{IN} = V _{CC} or GND, I _O = 0
Output leakage current	I _{OFF}	0	—	—	5	μA	V _{IN} or V _O = 0 to 3.6 V
Input capacitance	C _{IN}	3.3	—	4.5	—	pF	V _{IN} = V _{CC} or GND

Note: For conditions shown as Min or Max, use the appropriate values under recommended operating conditions.

Switching Characteristics

(Ta = -40 to 85°C)

V_{CC} = 1.2 V

Item	Symbol	Min	Typ	Max	Unit	Test conditions	FROM (Input)	TO (Output)
Maximum clock frequency	f _{max}	—	200	—	MHz	C _L = 15 pF		
Propagation delay time	t _{PLH}	—	9.0	—	ns	C _L = 15 pF	$\overline{\text{PRE}}/\overline{\text{CLR}}$	Q or $\overline{\text{Q}}$
	t _{PHL}	—	10.5	—			CLK	
Setup time	t _{su}	—	5.0	—	ns		D	
		—	-3.0	—			$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ inactive	
Hold time	t _h	—	-5.0	—	ns			
Pulse width	t _w	—	3.0	—	ns		$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ "L"	
		—	3.0	—			CLK "H" or "L"	

V_{CC} = 1.5±0.1 V

Item	Symbol	Min	Typ	Max	Unit	Test conditions	FROM (Input)	TO (Output)
Maximum clock frequency	f _{max}	100	350	—	MHz	C _L = 15 pF		
Propagation delay time	t _{PLH}	2.0	—	11.0	ns	C _L = 15 pF	$\overline{\text{PRE}}/\overline{\text{CLR}}$	Q or $\overline{\text{Q}}$
	t _{PHL}	2.0	—	11.0			CLK	
Setup time	t _{su}	4.5	—	—	ns		D	
		5.0	—	—			$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ inactive	
Hold time	t _h	0.0	—	—	ns			
Pulse width	t _w	3.5	—	—	ns		$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ "L"	
		3.5	—	—			CLK "H" or "L"	

HD74ALVC2G74 $V_{CC} = 1.8 \pm 0.15 \text{ V}$

Item	Symbol	Min	Typ	Max	Unit	Test conditions	FROM (Input)	TO (Output)
Maximum clock frequency	f_{max}	160	350	—	MHz	$C_L = 30 \text{ pF}$		
Propagation delay time	t_{PLH}	1.5	—	8.0	ns	$C_L = 30 \text{ pF}$	$\overline{PRE}/\overline{CLR}$	Q or \overline{Q}
	t_{PHL}	1.5	—	8.0			CLK	
Setup time	t_{su}	3.5	—	—	ns		D	
		3.0	—	—			\overline{PRE} or \overline{CLR} inactive	
Hold time	t_h	0.0	—	—	ns			
Pulse width	t_w	2.5	—	—	ns		\overline{PRE} or \overline{CLR} "L"	
		2.5	—	—			CLK "H" or "L"	

 $V_{CC} = 2.5 \pm 0.2 \text{ V}$

Item	Symbol	Min	Typ	Max	Unit	Test conditions	FROM (Input)	TO (Output)
Maximum clock frequency	f_{max}	160	400	—	MHz	$C_L = 30 \text{ pF}$		
Propagation delay time	t_{PLH}	1.0	—	5.0	ns	$C_L = 30 \text{ pF}$	$\overline{PRE}/\overline{CLR}$	Q or \overline{Q}
	t_{PHL}	1.0	—	5.0			CLK	
Setup time	t_{su}	2.5	—	—	ns		D	
		2.0	—	—			\overline{PRE} or \overline{CLR} inactive	
Hold time	t_h	0.0	—	—	ns			
Pulse width	t_w	2.0	—	—	ns		\overline{PRE} or \overline{CLR} "L"	
		2.0	—	—			CLK "H" or "L"	

 $V_{CC} = 3.3 \pm 0.3 \text{ V}$

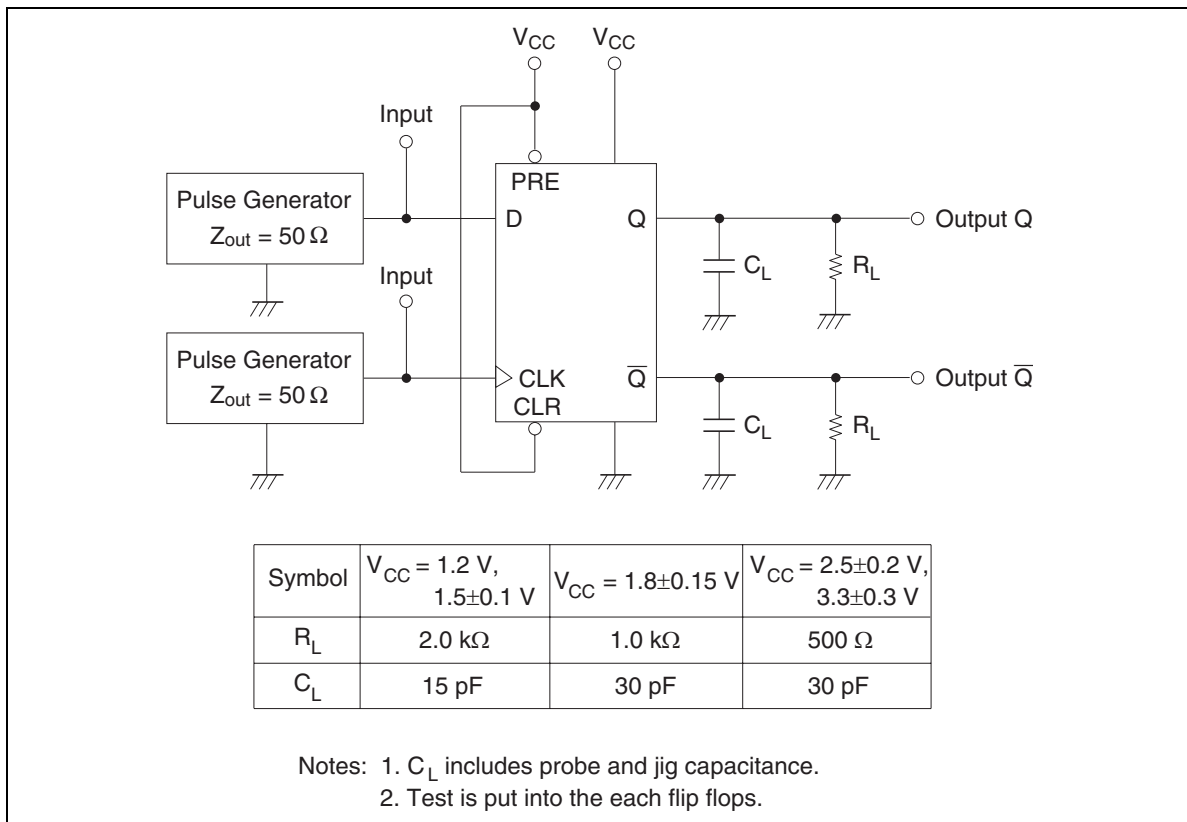
Item	Symbol	Min	Typ	Max	Unit	Test conditions	FROM (Input)	TO (Output)
Maximum clock frequency	f_{max}	200	450	—	MHz	$C_L = 30 \text{ pF}$		
Propagation delay time	t_{PLH}	1.0	—	3.5	ns	$C_L = 30 \text{ pF}$	$\overline{PRE}/\overline{CLR}$	Q or \overline{Q}
	t_{PHL}	1.0	—	3.5			CLK	
Setup time	t_{su}	2.0	—	—	ns		D	
		2.0	—	—			\overline{PRE} or \overline{CLR} inactive	
Hold time	t_h	0.0	—	—	ns			
Pulse width	t_w	2.0	—	—	ns		\overline{PRE} or \overline{CLR} "L"	
		2.0	—	—			CLK "H" or "L"	

Operating Characteristics

($T_a = 25^\circ\text{C}$)

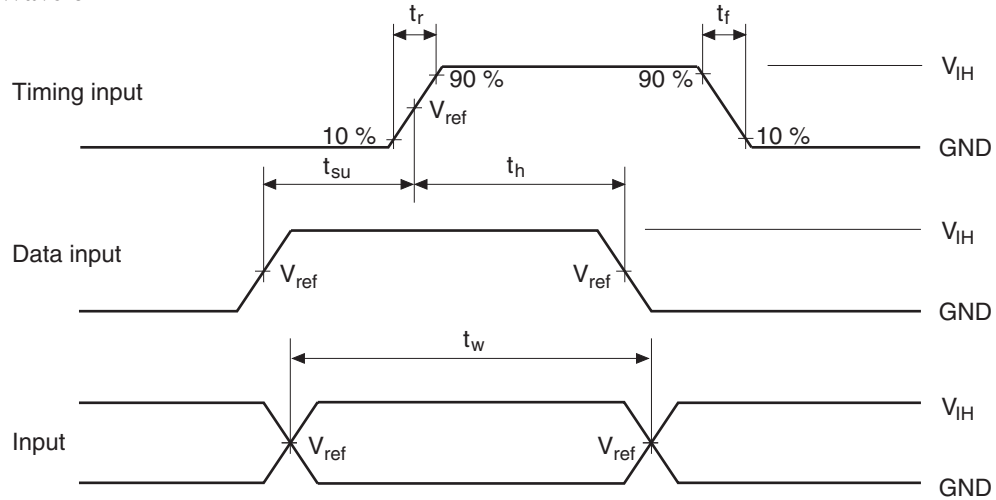
Item	Symbol	V_{CC} (V)	Min	Typ	Max	Unit	Test conditions
Power dissipation capacitance	C_{PD}	1.5	—	13.5	—	pF	$f = 10\text{ MHz}$
		1.8	—	13.5	—		
		2.5	—	20.0	—		
		3.3	—	22.0	—		

Test Circuit

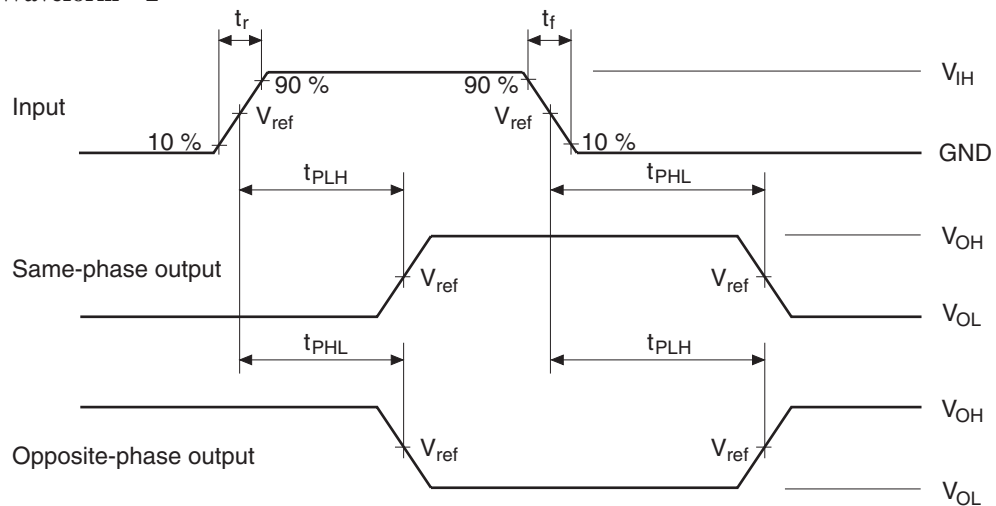


Waveforms

• Waveform – 1



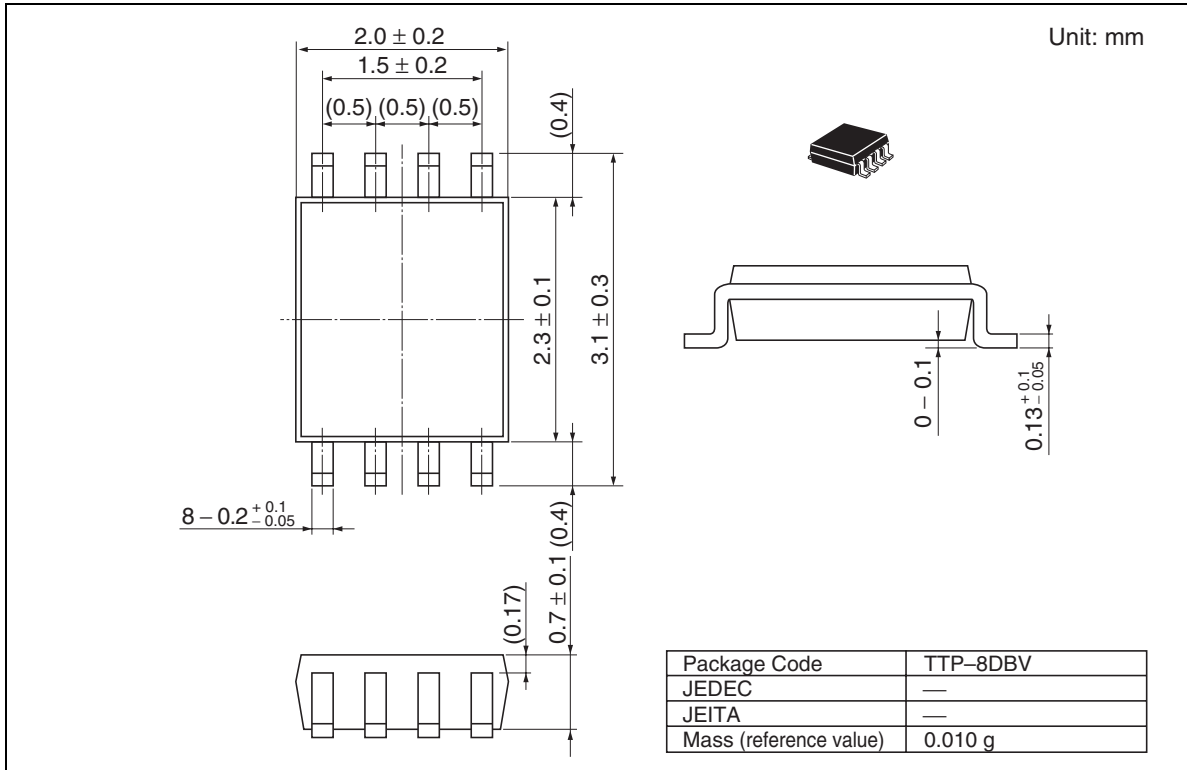
• Waveform – 2



Symbol	$V_{CC} = 1.2 \text{ V},$ $1.5 \pm 0.1 \text{ V},$ $1.8 \pm 0.15 \text{ V}$	$V_{CC} = 2.5 \pm 0.2 \text{ V}$	$V_{CC} = 3.3 \pm 0.3 \text{ V}$
t_r / t_f	2.0 ns	2.5 ns	2.5 ns
V_{IH}	V_{CC}	V_{CC}	2.7 V
V_{ref}	50%	50%	1.5 V

Note: Input waveform : PRR = 10 MHz, duty cycle 50%

Package Dimensions



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